

# **PRODUCT SPECIFICATION**

**6.8" TFT LCD MODULE** 

MODEL: TFTL-0107 Ver:1.0

< >> Preliminary Specification

< ◆> Finally Specification

CUSTOMER'S APPROVAL					
CUSTOMER:					
SIGNATURE: DATE:					

APPROVED	PM	PD	PREPARED
ВУ	REVIEWED	REVIEWED	BY

# **Revision History**

Revision	Date	Originator	Detail	Remarks
1.0	2016.09.13	ZFY	Initial Release	

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### 1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver lcs and a backlight unit.

#### 2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	6.8"	
LCD type	IPS TFT	
Display Mode	Transmissive /Normally black	
Resolution	480 RGB x 1280	Pixels
View Direction	FULL VIEW	Best Image
Module Outline	66.12(H) x 171.79 (V) x 2.5 (T) (Note1)	mm
Active Area	60.22 (H) x 160.59 (V)	mm
Pixel Size	125.46 (H) x 125.46 (V)	um
Pixel Arrangement	Stripe	
Display Colors	16.7M	
Interface	MIPI	
With or without touch panel	Without	
Driver IC	EK79030	-
Operating Temperature	-20~60	°C
Storage Temperature	<b>-20∼65</b>	°C
Weight	TBD	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

### 3. Absolute Maximum Ratings

V<sub>SS</sub>=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VCI	2.5	6.0	V
Supply Voltage	IOVCC	1.8	5.5	
Storage temperature	T <sub>STG</sub>	-20	+65	°C
Operating temperature	T <sub>OP</sub>	-20	+60	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

#### 4. DC Characteristics

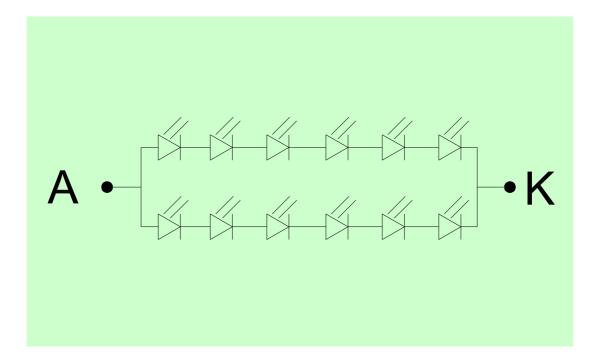
Item	Symbol	Min.	Тур.	Max.	Unit	
Complex Veltages		VCI	2.5	3.3	3.6	V
Supply Voltage		IOVCC	1.8	3.3	3.6	
VDDIO Input low level voltage		$V_{IL}$	VSS	-	0.2*IOVCC	mV
VDDIO Input high level voltage		V <sub>IH</sub>	0.8*IOVCC	-	IOVCC	mV
Current Consumption Logic		Icc+ lin	_	TBD	_	mA
All Black	Analog	ICC+ IIIV	_	טטו	_	ША

## 5. Backlight Characteristic

#### 5.1. Backlight Characteristic

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF	Ta=25 °C, I <sub>F</sub> =20mA/LED	16.8	19.2	20.4	V
Forward Current	lF	Ta=25 °C, V <sub>F</sub> =3.2V/LED	-	20*2	-	mA
Power dissipation	PD		-	768	-	mW
Uniformity	Avg		70	-	-	%
Drive method	Constant current					
LED Configuration	12 V	Vhite LEDs (6 LEDs in one	string an	d 2 group	s in para	llel)

### 5.2. Backlight Characteristic



## 6. Optical Characteristics

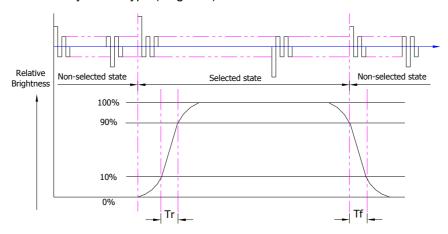
### 6.1. Optical Characteristics

Ta=25°C, VCI=3.3V, TN LC+ Polarizer

	Item	•	Symbol	Condition	S	pecificati	on	Unit
	Item		Syllibol	Condition	Min.	Тур.	Max.	Offic
	Luminance on ${\sf TFT}(I_f = 20 {\sf mA/LED})$							
ode)			Lv	Normally	320	400	-	cd/m²
	Contrast ratio	(See 6.3)	CR	viewing angle	700	900	-	
Backlight On (Transmissive Mode)	Response time (See 6.2)		TR+TF	$\theta x = \phi Y = 0^{\circ}$	-	25	35	ms
mis	Chromaticity Transmissive (See 6.5)	Red	XR			TBD		
(Trans		Reu	YR			TBD		
		missive	XG			TBD		
O			YG			TBD		
jht			Хв			TBD		
N Sign			Yв			TBD		
3ac			Xw			TBD		
"		VVIIILE	Yw			TBD		
		Horizontal	θх+		70	80	-	
	Viewing Angle	TIONZONIA	θх-	Center CR≥10	70	80	-	Dog
	(See 6.4)	Vertical	φY+	Center CR210	70	80	-	Deg.
		vertical	φY-		70	80	-	
	NTSC Ratio	(Gamut)			-	60	-	%

## 6.2. Definition of Response Time

#### 6.2.1. Normally Black Type (Negative)

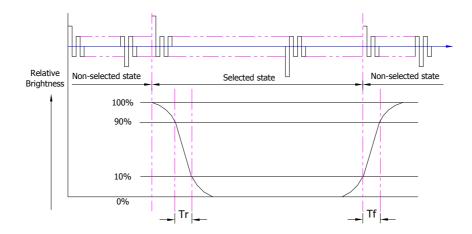


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

#### 6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

#### 6.3. Definition of Contrast Ratio

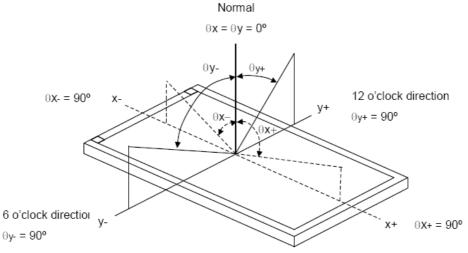
Contrast is measured perpendicular to display surface in reflective and transmissive mode.

The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Toot nottorn	A: All Pixels white
Test pattern	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

### 6.4. Definition of Viewing Angles

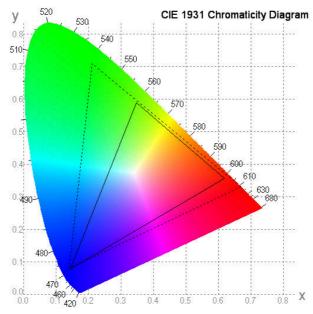


Measuring machine: LCD-5100 or EQUI

#### 6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

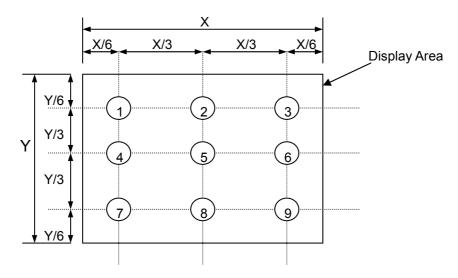


#### 6.6. Definition of Surface Luminance, Uniformity and Transmittance

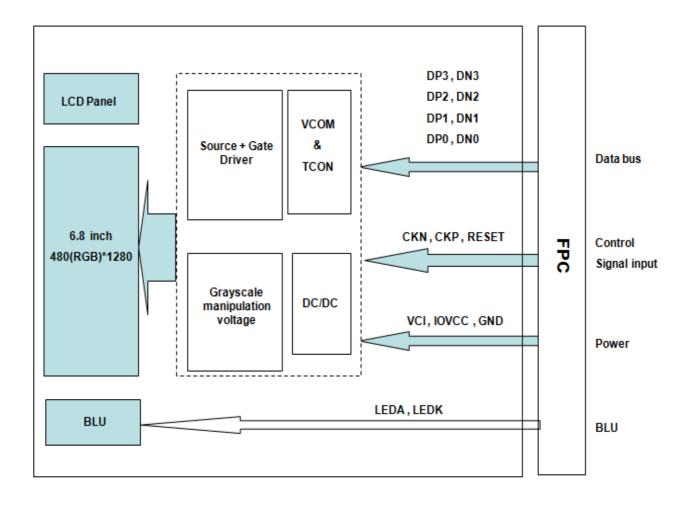
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance:  $L_V$  = average ( $L_{P1}$ : $L_{P9}$ )
- 6.6.2. Uniformity = Minimal  $(L_{P1}:L_{P9})$  / Maximal  $(L_{P1}:L_{P9})$  \* 100%
- 6.6.3. Transmittance =  $L_V$  on LCD /  $L_V$  on Backlight \* 100%

Note: Measuring machine: BM-7



# 7. Block Diagram and Power Supply



# 8. Interface Pins Definition

No.	Symbol	Function	Remark
1	GND	Ground	
2	VCI	A power supply for DC/DC circuit	
3	VCI	A power supply for DC/DC circuit	
4	IOVCC	A power supply for the I/O circuit	
5	GND	Ground	
6	RESET	Reset pin	
7	TE	No connection	
8	GND	Ground	
9	GND	Ground	
10	DN3	MIPI data Input	
11	DP3	MIPI data Input	
12	GND	Ground	
13	DN2	MIPI data Input	
14	DP2	MIPI data Input	
15	GND	Ground	
16	CKN	MIPI clock Input	
17	CKP	MIPI clock Input	
18	GND	Ground	
19	DN1	MIPI data Input	
20	DP1	MIPI data Input	
21	GND	Ground	
22	DN0	MIPI data Input	
23	DP0	MIPI data Input	
24	GND	Ground	
25	GND	Ground	
26	LEDK	Led cathode	
27	LEDK	Led cathode	
28	LEDA	Led anode	
29	LEDA	Led anode	
30	NC	No connection	

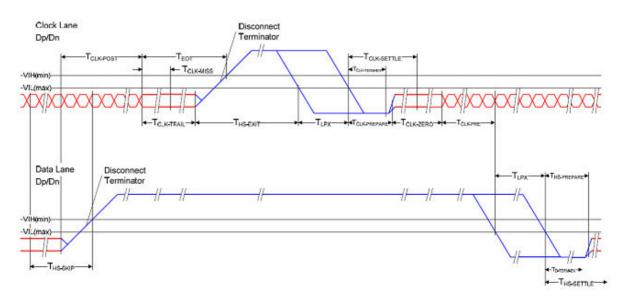
### 9. AC Characteristics

## 9.1. MIPI Input timing

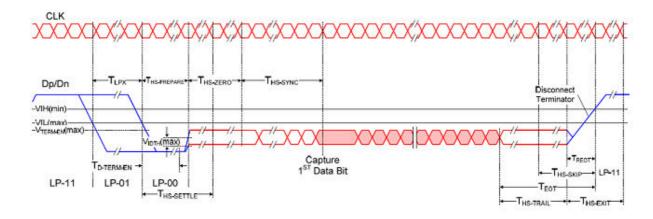
For 480RGBx1280

:	Symbol		Value		Unit
	Syllibol	Min.	Тур.	Max.	Offic
MIPI (4 Lane) @Frame rate=60Hz			386		Mbps
Lane) @Frame rate=60Hz			515		Mbps
DCLK frequency @Frame rate=60Hz	Focik		64.4		MHz
HSYNC period time	Тн		824		DCLK
Horizontal display area	Тно		480		DCLK
HSYNC pulse width	THPW		24	-	DCLK
HSYNC back porch	Тнвр		160	-	DCLK
HSYNC front porch	Тғар		160	-	DCLK
VSYNC period time	Tv		1304		Н
Vertical display area	Tvo		1280		Н
VSYNC pulse width	Tvpw		2	-	Н
VSYNC back porch	Tvap		10	-	Н
VSYNC front porch	TVFP		12	-	Н

#### 9.2. MIPI AC characteristics



Switching the clock lane between clock transmission and low-power mode



Timing of high-speed data transmission in bursts

Parameter	Bint	Spec.			Unit
Parameter	Descript	Min.	Тур.	Max.	Unit
T <sub>REOT</sub>	30%-85% rise time and fall time	-	-	35	ns
T <sub>CLK-MISS</sub>	Timeout for receiver to detect absence of Clock transitions and disable the Clock Lane HS-RX.	-	-	60	ns
T <sub>CLK-POST</sub> *1	Time that the transmitter continues to send HS dock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of T <sub>HS-TRAIL</sub> to the beginning of T <sub>CLK-TRAIL</sub> .		-		ns
T <sub>CLK-PRE</sub>	Time that the HS clock shall be driven by the transmitter prior to any associated Data Lane beginning the transition from LP to HS mode.	8	-		ns
T <sub>CLK-SETTLE</sub>	Time interval during which the HS receiver shall ignore any Clock Lane HS transitions, starting from the beginning of Tolk-PRE.	95	-	300	ns
T <sub>CLK-TERM-EN</sub>	Time for the Clock Lane receiver to enable the HS line termination, starting from the time point when Dn crosses $V_{\rm ILMAX}$ .	Time for Dn to reach VTERM-EN	-	38	ns
T <sub>HS-SETTLE</sub>	Time interval during which the HS receiver shall ignore any Data Lane HS transitions, starting from the beginning of THSPREPARE.		-	145 ns + 10*UI	ns
T <sub>EOT</sub>	Time from start of T <sub>HS-TRAIL</sub> or T <sub>CLK-TRAIL</sub> period to start of LP-11 state	-	-	105ns+48*UI	-

T <sub>HS-EXIT</sub> <sup>(1)</sup>	time to drive LP-11 after HS burst	100	-	-	ns
T <sub>HS-PREPARE</sub>	Time to drive LP-00 to prepare for HS transmission	40ns + 4*UI	-	85ns+6*UI	ns
T <sub>HS-PREPARE</sub> + T <sub>HS-ZERO</sub>	T <sub>HS-PREPARE</sub> + Time to drive HS-0 before the Sync sequence	145ns + 10*U	-	-	ns
T <sub>HS-SKIP</sub>	Time-out at RX to ignore transition period of EoT	40	-	55ns+4*UI	ns
T <sub>HS-TRAIL</sub>	Time to drive flipped differential state after last payload data bit of a HS transmission burst	60 + <b>4*</b> UI	-	-	ns
T <sub>LPX</sub>	Length of any Low-Power state period	50	-	-	ns
Ratio T <sub>LPX</sub>	Ratio of T <sub>LPX(MASTER)</sub> /T <sub>LPS(SLAVE)</sub> between Master and Slave side	2/3	-	3/2	-
T <sub>TA-GET</sub> Time to drive LP-00 by new TX		5*T <sub>LPX</sub>			ns
T <sub>TA-GO</sub>	Time to drive LP-00 after Turnaround Request	Turnaround Request 4*T <sub>LPX</sub>		ns	
T <sub>TA-SURE</sub>	Time-out before new TX side starts driving	2*T <sub>LPX</sub>	ns		

Note: (1) For image transmission:

TCLK-POST min value =164 when MIPI max frequency per lane = 0.53Gbps.

TCLK-POSTMIN value =112 when MIPI max frequency per lane = 1Gbps

## 10. Reset timing

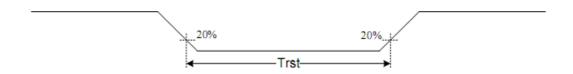
When RESETB of the reset pin equals to Low, it will be in the condition of reset. When it is in the condition of reset, it will make the device recover the initial set.

However, in order to avoid the reset noise cause reset, there is a mechanism to judge about whether the reset is needed or not.

The closed interval of Low can be shown as the following.

(Test condition: VDDIO=1.65V~3.6V, VSS=0V, TA=-20 ~+85)

Davamatar	Symbol	Conditions	Spec.			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max	Onit
Reset low pulse width	Trst		20	-	•	μs



### 11. Quality Assurance

#### 11.1. Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

#### 11.2. Standard for Quality Test

11.2.1 Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

11.2.2 Sampling Criteria:

Visual inspection: AQL 1.5% Electrical functional: AQL 0.65%.

11.2.3 Reliability Test:

Detailed requirement refer to Reliability Test Specification.

#### 11.3. Nonconforming Analysis & Disposition

- 11.3.1 Nonconforming analysis:
  - 11.3.1.1 Customer should provide overall information of non-conforming sample for their complaints.
  - 11.3.1.2 After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
  - 11.3.1.3 If cannot finish the analysis on time, customer will be notified with the progress status.
- 11.3.2 Disposition of nonconforming:
  - 11.3.2.1 Non-conforming product over PPM level will be replaced.
  - 11.3.2.2 The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

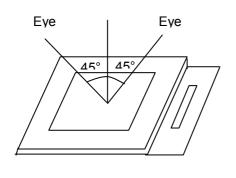
#### 11.4. Agreement Items

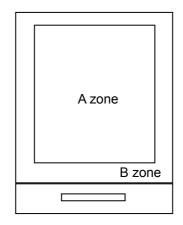
Shall negotiate with customer if the following situation occurs:

- 11.4.1 There is any discrepancy in standard of quality assurance.
- 11.4.2 Additional requirement to be added in product specification.
- 11.4.3 Any other special problem.

#### 11.5. Standard of the Product Visual Inspection

- 11.5.1 Appearance inspection:
  - 11.5.1.1 The inspection must be under illumination about 1000 1500 lx, and the distance of view must be at 30cm ± 2cm.
  - 11.5.1.2 The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.
  - 11.5.1.3 Definition of area: A Zone: Active Area, B Zone: Viewing Area,





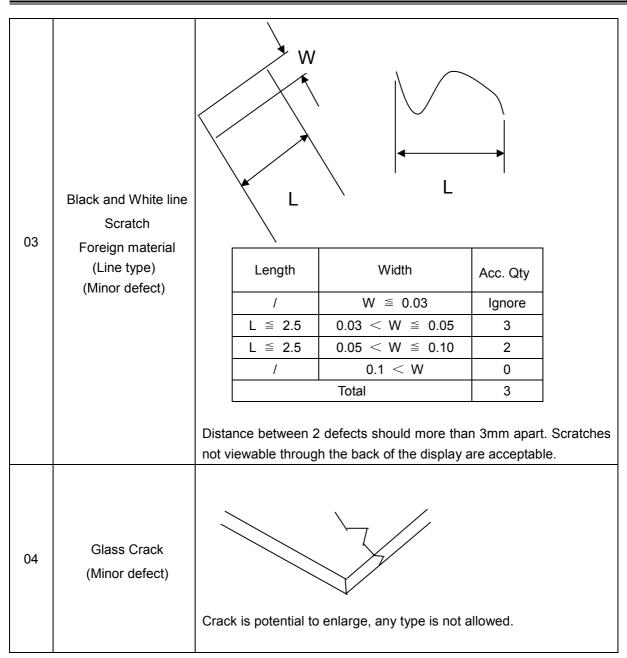
### 11.5.2 Basic principle:

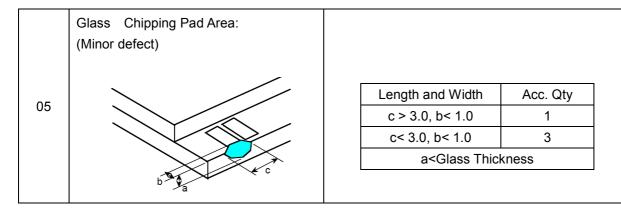
11.5.2.1 A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

11.5.2.2 New item must be added on time when it is necessary.

### 11.6. Inspection Specification

No.	Item	Criteria (Unit: mm)			
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	$\phi = (a + b)/2$ Distance between 2	φ≤0.2 0.20<φ≤ 0.50<0	20 Ig 0.50 N	c. Qty nore ≤3 0
		Distance between 2		•	
			Display Area	Total	
		Bright dot	N≤2	N≤2	Note1
		Dark dot	N≤4	N≤4	
02	Electrical Defect	Total dot	N≤4	N≤4	
02	(Minor defect)	Mura	Not visible through	gh 5% ND filters.	Note 2
		Remark: 1. Bright dot caused	by scratch and fore	ign object accord	s to item 1.





	Glass Chipping Rear of Pad Area:		
	(Minor defect)	Length and Width	Acc. Qty
06		c > 3.0, b< 1.0	1
		c< 3.0, b< 1.0	2
		c< 3.0, b< 0.5	4
	c	a <glass td="" thick<=""><td>iness</td></glass>	iness
	b va		
	Glass Chipping Except Pad Area: (Minor defect)		
	(William derest)	Length and Width	Acc. Qty
		c > 3.0, b< 1.0	1
07		c< 3.0, b< 1.0	2
	b	c< 3.0, b< 0.5	4
	To the state of th	a <glass td="" thick<=""><td>iness</td></glass>	iness
	a 🔨		
	Glass Corner Chipping:		
	(Minor defect)	Length and Width	Acc. Qty
		c < 3.0, b< 3.0	Ignore
08		a <glass td="" thick<=""><td></td></glass>	
	ba		
	Glass Burr:		
	(Minor defect)		
	F	Length	Acc. Qty
09		F < 1.0	Ignore
	, F , .		
		Glass burr don't affect ass	emble and module
		dimension.	

10	FPC Defect: (Minor defect)		10.1 Dent, pinhole (w: circuitry width. 10.2 Open circuit 10.3 No oxidation.	) is unacceptable.	
11	Bubble on Polarizer (Minor defect)		Diameter $φ ≤ 0.20$ 0.20 $< φ ≤ 0.30$ 0.30 $< φ ≤ 0.50$ 0.50 $< φ$	Acc. Qty Ignore 4 1 None	
12	Dent on Polarizer (Minor defect)		Diameter $φ \le 0.20$ $0.20 < φ \le 0.30$ $0.30 < φ \le 0.50$ $0.50 < φ$	Acc. Qty Ignore 4 1 None	
13	Bezel	<ul><li>13.1 No rust, distortion on the Bezel.</li><li>13.2 No visible fingerprints, stains or other contamination.</li></ul>			
14	Touch Panel	D: Diameter W: width L: length  14.1 Spot: D<0.25 is acceptable  0.25 ≤ D ≤ 0.4  2dots are acceptable and the distance between defects should more than 10 mm.  D>0.4 is unacceptable  14.2 Dent: D>0.40 is unacceptable  14.3 Scratch: W≤0.03, L≤10 is acceptable,  0.03 <w≤0.10, 10="" 2="" acceptable="" between="" defects="" distance="" is="" l≤10="" mm.="" more="" should="" than="" w="">0.10 is unacceptable.</w≤0.10,>			
15	РСВ	15.1 No distortion or contamination on PCB terminals. 15.2 All components on PCB must same as documented on the BOM/component layout. 15.3 Follow IPC-A-600F.			

16	Soldering	Follow IPC-A-610C standard
17	Electrical Defect (Major defect)	The below defects must be rejected.  17.1 Missing vertical / horizontal segment,  17.2 Abnormal Display.  17.3 No function or no display.  17.4 Current exceeds product specifications.  17.5 LCD viewing angle defect.  17.6 No Backlight.  17.7 Dark Backlight.  17.8 Touch Panel no function.

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

#### 11.7. Classification of Defects

- 11.7.1 Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 11.7.2 Two minor defects are equal to one major in lot sampling inspection.

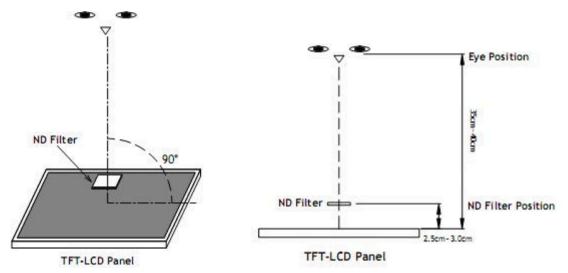
#### 11.8. Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

#### 11.9. Packaging

- 11.9.1 There should be no damage of the outside carton box, each packaging box should have one identical label.
- 11.9.2 Modules inside package box should have compliant mark.
- 11.9.3 All direct package materials shall offer ESD protection

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is  $350 \text{mm} \pm 50 \text{mm}$ .

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is  $350 \text{mm} \pm 50 \text{mm}$ .

**Note2:** Mura on display which appears darker / brighter against background brightness on parts of display area.

# 12. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	60℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	40℃, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	65℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-20℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20°C, 60min ~ 60°C, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	2	GB/T5170.14 -2009
8	Electrical Static Discharge	Air: $\pm$ 4KV 150pF/330 $\Omega$ 5 times	2	GB/T17626.2
	Lieutical Static Discharge	Contact: $\pm$ 2KV 150pF/330 $\Omega$ 5 times	2	-2006
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

16	Soldering	Follow IPC-A-610C standard
17	Electrical Defect (Major defect)	The below defects must be rejected.  17.1 Missing vertical / horizontal segment,  17.2 Abnormal Display.  17.3 No function or no display.  17.4 Current exceeds product specifications.  17.5 LCD viewing angle defect.  17.6 No Backlight.  17.7 Dark Backlight.  17.8 Touch Panel no function.

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- 11.7.1 Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 11.7.2 Two minor defects are equal to one major in lot sampling inspection.

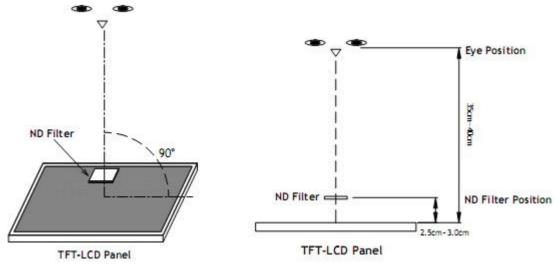
#### 11.8. Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

#### 11.9. Packaging

- 11.9.1 There should be no damage of the outside carton box, each packaging box should have one identical label.
- 11.9.2 Modules inside package box should have compliant mark.
- 11.9.3 All direct package materials shall offer ESD protection

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is  $350 \text{mm} \pm 50 \text{mm}$ .

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is  $350 \text{mm} \pm 50 \text{mm}$ .

**Note2:** Mura on display which appears darker / brighter against background brightness on parts of display area.

#### 13.4.2.6. Solder Wetting



Recommended

Not Recommended

13.4.2.7. The type of the solder iron:



Recommended

Not Recommended

13.4.2.8. Solder Pad



#### 13.5. Operation

13.5.1. Do not drive LCD with DC voltage

13.5.2. Response time will increase below lower temperature

13.5.3. Display may change color with different temperature

13.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".

#### 13.6. Static Electricity

- 13.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 13.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 13.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

#### 13.7. Limited Warranty

- 13.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 13.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 13.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

# 14. Packaging

TBD

## 15. Outline Drawing

